PRODUCT INFORMATION BULLETIN



OVERVIEW

PACO•**VIA[™] 3000** is a two-sided release film designed to be part of a Two-Component System (PACO•VIA[™] 3000 and PACOPADS[™]) as a performance-driven line of High-Temperature, Resin-Blocking Release Films. The PACO•VIA[™] 3000 System is specifically engineered to enhance sequential lamination of Buried and Blind Via designed rigid printed Circuit Boards.

LAMINATION PROCESS ADVANTAGES

- Resin Containment PACO-VIA[™] 3000 Resin-Blocking Film contains the resin within the via barrel eliminating the need for secondary processing to remove cured resin from the panel surface
- **Barrel Fill** PACO•VIA[™] 3000 Resin Blocking Film allows the liquid resin to essentially fill the via Barrel
- Contain Resin Squeeze-out- PACO•VIA™ 3000 contains resin squeeze-out like traditional release films while offering superior copper surface buffering from damaged Separator Plates
- Equalization of Pressure throughout the Pressure Load - The PACOPADS[™] component of the PACO•VIA[™] 3000 System ensures complete barrel fill, and controlled Dielectric Thickness. PACOPADS[™] eliminate air voids, inner-layer slippage and white corners or edges. PACOPADS[™] also reduce image and glass cloth Transfer, and alleviate the potential of low-pressure prepreg Blisters.

PACO • VIA

BLIND VIA HOLE LAMINATING FILM

PACO•VIA™ 3000

FEATURES

- Two engineered Grades to fit all sequential lamination demands
- Choice of PACOPADS[™] Pressure Equalizing Press Pads designed to suit all lamination process parameters
- Operating temperature of 425°F / 218°C for up to 4 hours
- Essentially inert, no out-gassing, plate residue, interlaminate adhesion influence, no vacuum system contamination
- Environmentally friendly: no chrome-depleting chemicals, no Fluorine's
- The PACO•VIA[™] 3000 System is designed to contain the resin flow within Blind Via Holes (onto adjacent coppercarrying layers) and to fill buried Via Barrels, under a wide range of Lamination Pressures (175-350 psi/12-24 kg/ cm2), Hole Diameters (.004 to .040"/0.1 to 1.0mm), Heat Rises and Prepreg types
- The PACO-VIA[™] 3000 System performs effectively well in Hydraulic and Hydraulic Vacuum-assist as well as with both stainless steel and aluminum Separator Plates. Steel is preferred
- The PACO•VIA[™] 3000 System is suitable for all resin system types when laminated within the listed temperature constraints

RECOMENDED LAMINATION LAY-UP





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DESCRIPTION OF STANDARDS

Physical Property		Test Method		Reported Units	Typical Values
Max. Application Temp.		Q 1025		°F (°C)	425(218)
Thickness		Q 3019		Mils	3.25/75µ
Density		ASTM		g/cm3	0.94
Heat Shrinkage		MD	Pacothane	%	<5%
		ID	Method		<5%
Melting Temp.		ASTM E794		°C	218°C
Appearance		White, Semi-translucent			
Tensile Strength (At yeild point)	MD	ΥP	ASTM D882	Kg/cm2	230
		Elong	ASTM D882	%	410
	TD	ΥP	ASTM D882	Kg/cm2	190
		Elong	ASTM D882	%	520



BLIND VIA HOLE LAMINATING FILM

PACO•VIA™ 3000

AVAILABILITY

PACO•VIA[™] 3000 Conformal Release Film

is available in rolls and in custom-made sheet sizes, tooled to customer specifications. The complete line of Pacothane® products is available from leading local Distributors Worldwide who offer "Just in Time" delivery from locally-available stocks.

Also from Pacothane® Technologies:



Information contained in this technical literature is believed to be accurate and is offered in good faith for the benefit of the consumer. Inasmuch as Pacothane® Technologies has no control over the use to which others may put the material, it does not guarantee that the same results as those described herein will be obtained. Each user of the material should make his own tests to determine the material's suitability for his own particular use. Statements concerning possible or suggested uses of the materials described herein are not to be construed as constituting a license under any Pacothane® Technologies patent or application covering such use or as recommendations for use of such materials in the infringement of any patent.

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